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SUPPLEMENTARY INFORMATION

2D PC₃ as a Promising Thermoelectric Material

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Fig. S1 Profiles of (a) thermal conductivity, (b) electrical conductivity and (c) Seebeck coefficient under uniaxial compressive and tensile strains on PC₃.



Fig. S2 Profiles of (a) thermal conductivity, (b) electrical conductivity and (c) Seebeck coefficient under biaxial compressive and tensile strains on PC₃.